

What Is Claimed Is:

1. A module for containing a circuit, the module comprising:
a housing having a front having a certain thickness; and
a receptacle accessible from the front of the housing, the receptacle shaped to receive a circuit component wherein the receptacle forms a waveguide.
2. A module according to claim 1 further comprising a plurality of receptacles accessible from the front of the housing wherein each receptacle is shaped to receive an individual circuit component and each receptacle forms a waveguide.
3. A module according to claim 1 wherein the receptacle has the shape of a rectangular chamber.
4. A module according to claim 1 wherein the front of the housing is recessed in a region surrounding the receptacle.
5. A module according to claim 4 further comprising a cover shaped to fit within the recess wherein the cover extends over the receptacle.
6. A module according to claim 5 further comprising a means for attaching the cover to the front wall of the housing.
7. A module according to claim 5 further comprising a snapping barb for securing the cover to the front of the housing.
8. A module according to claim 1 wherein the circuit component is a removable plug, the module further comprising:
a circuit board located in the interior of the housing wherein the circuit board has a conductive pathway on a first side of the circuit board and a second conductive pathway on a second surface of the circuit board opposite the first surface; and

a plug connector mounted on the circuit board for receiving the plug, wherein the plug has a first terminal and a second terminal extending from a back portion of the plug so that the first and second terminals are exposed in the back portion wherein the plug fits in the receptacle and is received in the plug connector and the first terminal is electrically coupled to the first conductive pathway on the first surface of the circuit board and the second terminal is electrically coupled to the second conductive pathway on the second surface of the circuit board.

9. A module according to claim 8 wherein the plug includes a third terminal located between the first and second terminals wherein the third terminal extends into the circuit board.
10. A module according to claim 9 wherein the circuit board is a layered circuit board and has a ground plane located in a center layer, wherein the third terminal of the plug contacts the ground plane layer of the circuit board.
11. A module according to claim 1 wherein the thickness of the front of the housing ranges from about .2 to about .8 inches.
12. A module according to claim 11 wherein the thickness is about .25 inches.
13. A module according to claim 11 wherein the thickness is about .75 inches.
14. A module according to claim 8 wherein the plug has a plastic housing and circuitry located in the plastic housing near the back portion of the plug so that when the plug is inserted in the receptacle and received by the plug connector, the circuitry is located in an interior of the housing.
15. A module according to claim 1 wherein the housing is made of a conductive material.

16. A module according to claim 5 wherein the cover is made of a nonconductive material.
17. A module according to claim 5 wherein the cover when placed in the recessed opening of the front obstructs access to the receptacle.
18. A module according to claim 14 wherein the circuitry includes an attenuator circuit.
19. A module according to claim 8 further comprising a plurality of coax connectors secured to a back of the housing; and a plurality of connection locations on the circuit board wherein the coax connectors are coupled to the connection locations.
20. A module according to claim 19 wherein the circuit board includes a plurality of circuit components interconnected with one another and with the connection locations through a plurality of circuit paths wherein the plurality of circuit components includes splitter components for receiving a main signal from one of the connection locations and dividing the main signal into a plurality of branch signals delivered along the circuit paths to individual remaining ones of the connection locations.
21. A module according to claim 19 wherein the circuit board includes a plurality of circuit components interconnected with one another and with the connection locations through a plurality of circuit paths wherein the plurality of circuit components includes combiner components for receiving a plurality of branch signals from individual ones of the connection locations and combining the branch signals into a main signal delivered along the circuit paths to a remaining one of the connection locations.
22. A module according to claim 5 wherein the module has an emission rating of greater than 100 dB down from a carrier signal when the cover is removed.

23. A module according to claim 1 wherein the housing is made of conductive material and the waveguide is formed by the thickness of the housing.
24. A module for containing a circuit, the module comprising:
a housing having a front wall and a rear wall, the front wall including a
conductive material;
rear connectors mounted at the rear wall; and
at least one receptacle defined through the front wall for receiving a circuit
component, the receptacle having a depth of sufficient magnitude to
choke emissions generated within the housing.
25. The module of claim 24, further comprising a front connector positioned
within the housing for interfacing with the circuit component, wherein the receptacle
is adapted to guide the circuit component into the front connector.
26. The module of claim 24, further comprising a plurality of the receptacles for
receiving a plurality of circuit components, each receptacle having a depth of
sufficient magnitude to choke emissions generated within the housing.
27. The module of claim 26, wherein each receptacle is sized to receive a single
one of the circuit components.
28. The module of claims 24 or 26, wherein the depth is greater than .15 inches.
29. The module of claims 24 or 26, wherein the depth is at least .2 inches.
30. The module of claims 24 or 26, wherein the depth is at least .3 inches.
31. The module of claim 24, further comprising a cover adapted to be mounted
over the receptacle.
32. The module of claim 31, wherein the cover includes metal.

33. The module of claim 31, wherein the cover includes a non-conductive material.
34. The module of claim 31, wherein the cover includes plastic.
35. The module of claim 31, wherein the cover includes at least a portion that is transparent.
36. The module of claims 24 or 26, wherein the circuit component or components include attenuator pads.
37. The module of claim 36, further comprising a cover for covering the attenuator pads, the cover being configured such that attenuation values of the attenuator pads can be determined without removing the cover from the housing.
38. The module of claim 24, wherein the module comprises splitter/combiner module and includes splitter/combiner circuitry, and wherein the circuit component comprises an attenuator pad.
39. A module for containing a circuit, the module comprising:
a housing having a front wall and a rear wall, the front wall including a
conductive material;
rear connectors mounted at the rear wall;
a front connector positioned within the housing adjacent to an interior side of
the front wall for connecting with a circuit component; and
at least one receptacle defined through the front wall at a location in
alignment with the front connector, the receptacle being defined by
one or more guide surfaces adapted for guiding the circuit component
through the front wall and into contact with the front connector.
40. The module of claim 39, further comprising splitter/combiner circuitry positioned within the housing, and wherein the circuit component comprises an attenuator pad.

41. A module for containing a circuit, the module comprising:
a housing having a front wall and a rear wall, the front wall including a
conductive material;
rear connectors mounted at the rear wall;
at least one receptacle defined through the front wall for receiving a circuit
component; and
a non-metallic cover for covering the receptacle.
42. The module of claim 31, further comprising splitter/combiner circuitry
positioned within the housing, and wherein the circuit component comprises an
attenuator pad.
43. The module of claim 42, wherein the cover includes at least a portion that is
transparent.
44. A module for containing a circuit, the module comprising:
a housing having a front wall and a rear wall, the front wall including a
conductive material;
rear connectors mounted at the rear wall;
a receptacle defined through the front wall;
an attenuator pad received within the receptacle; and
a cover for covering the attenuator pad, the cover being configured such that
an attenuation value provided on the attenuation pad can be
determined without removing the cover.